

# Resource Summary Report

Generated by [dkNET](#) on Aug 13, 2026

## Horiba: GR-300 Series Wafer Back Side Cooling System

RRID:SCR\_020075

Type: Tool

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### Proper Citation

Horiba: GR-300 Series Wafer Back Side Cooling System (RRID:SCR\_020075)

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### Resource Information

**URL:** [https://www.horiba.com/en\\_en/products/detail/action/show/Product/gr-300-series-713/](https://www.horiba.com/en_en/products/detail/action/show/Product/gr-300-series-713/)

**Proper Citation:** Horiba: GR-300 Series Wafer Back Side Cooling System (RRID:SCR\_020075)

**Description:** Can control gases used to cool back side of wafers that are fixed in position by electrostatic chuck system.

**Resource Type:** instrument resource

**Keywords:** Horiba, Wafer Back Side Cooling System, Instrument, Resource Equipment, Equipment, USEDit,

**Availability:** Commercially available

**Resource Name:** Horiba: GR-300 Series Wafer Back Side Cooling System

**Resource ID:** SCR\_020075

**Alternate IDs:** Model\_Number\_GR\_300

**Record Creation Time:** 20220129T080348+0000

**Record Last Update:** 20260808T190146+0000

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### Ratings and Alerts

No rating or validation information has been found for Horiba: GR-300 Series Wafer Back Side Cooling System.

No alerts have been found for Horiba: GR-300 Series Wafer Back Side Cooling System.

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## Data and Source Information

**Source:** [SciCrunch Registry](#)

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## Usage and Citation Metrics

We have not found any literature mentions for this resource.